



Material Content Data Sheet



Sales Product Name		IDH06G65C5		Issued		29. August 2013		
MA#		MA000989322						
Package		PG-TO220-2-1		Weight*		1966.05 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	siliconcarbide	409-21-2	0.475	0.02		242	
	noble metal	gold	7440-57-5	0.036	0.00		18	
	non noble metal	tin	7440-31-5	0.009	0.00	0.02	5	265
leadframe	non noble metal	iron	7439-89-6	0.753	0.04		383	
	inorganic material	phosphorus	7723-14-0	0.226	0.01		115	
wire	non noble metal	copper	7440-50-8	751.797	38.25	38.30	382390	382889
	non noble metal	aluminium	7429-90-5	0.447	0.02	0.02	227	227
encapsulation	organic material	carbon black	1333-86-4	9.111	0.46		4634	
	plastics	epoxy resin	-	100.219	5.10		50975	
	inorganic material	silicondioxide	60676-86-0	498.059	25.33	30.89	253329	308938
leadfinish	non noble metal	tin	7440-31-5	14.487	0.74	0.74	7368	7368
plating	non noble metal	nickel	7440-02-0	0.198	0.01		101	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.01	1	101
heatspreader	non noble metal	iron	7439-89-6	0.590	0.03		300	
	inorganic material	phosphorus	7723-14-0	0.177	0.01		90	
	non noble metal	copper	7440-50-8	589.466	29.98	30.02	299822	300212
*deviation	< 10%				Sum in total:	100,00		1000000

Important Remarks:

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